

# Instrumentation for Accelerator Based sub-GeV DM Searches

Cameron Bravo (SLAC)

There is an SOW for this work, last revised 5/22

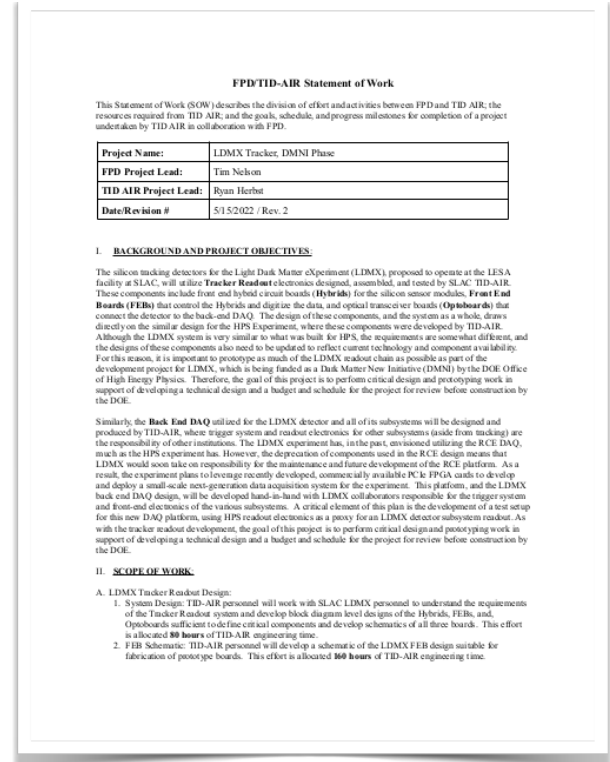
## Tracker readout design

- Front End Board (FEB)
  - schematic
  - layout
  - prototyping
  - testing
- Readout hybrids
  - schematic to define board size (based on HPS)

## Back end DAQ design/development

- System Design
- Bittware PCIe DAQ development
  - FPGA development
  - Testing with Tracker FEBs

SOW called for completion before end of FY22. More funding added in FY23 and expected in FY24. Important to keep on track for DOE reviews.



## *Routine updates and respins of previous designs (need to write an SOW)*

- Front End Board (FEB)
  - schematic revisions (minor)
  - layout revisions (minor)
  - turnkey production of 20 boards (parts in hand)
  - testing
- Flange Boards
  - schematic revision (old transceivers discontinued)
  - layout revision
  - production of 10 boards
- Readout hybrids
  - respin of existing design (~20 boards) to build more detector modules

With next HPS run in 2025, this has not been urgent, so have prioritized LDMX work. However, the funds have been sitting idle and have been vulnerable to poaching. Need to get going.

Thanks to Tim for this slide

# Readout Chips for Si Strip Trackers

- Limited quantities available of radiation hard front end chips for reading out Si strip sensors
  - APV25 production line at IBM decommissioned (0.25  $\mu\text{m}$ )
  - VFAT3 pad layout not ideal for Si strip sensors
  - ABC130 uses opposite polarity wrt sensors we have
- None of these chips have all the features that would be “ideal” for our types of experiments
  - Analog readout for charge interpolation
  - Buffer depth to enable LHC Run3 scale trigger latency
  - Fixed latency binary data for track triggering
- Hard to justify new ASIC just for us, we make the scraps work